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FQP2N40

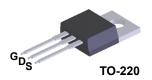
N-Channel QFET $^{\rm @}$ MOSFET 400 V, 1.8 A, 5.8 Ω

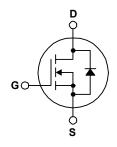
Description

This N-Channel enhancement mode power MOSFET is produced using ON Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 1.8 A, 400 V, $\rm R_{DS(on)}$ = 5.8 Ω (Max.) @ $\rm V_{GS}$ = 10 V, $\rm I_D$ = 0.9 A
- Low Gate Charge (Typ. 4.0 nC)
- Low Crss (Typ. 3.0 pF)
- · Fast Switching
- 100% Avalanche Tested
- · Improved dv/dt Capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQP2N40-F080	Unit
V_{DSS}	Drain-Source Voltage		400	V
I _D	Drain Current - Continuous (T _C = 25°	°C)	1.8	Α
	- Continuous (T _C = 100)°C)	1.14	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	7.2	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	85	mJ
I _{AR}	Avalanche Current	(Note 1)	1.8	А
E _{AR}	Repetitive Avalanche Energy	(Note 1)	4.0	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P_{D}	Power Dissipation (T _C = 25°C)		40	W
	- Derate above 25°C		0.32	W/°C
T _J , T _{STG}	Operating and Storage Temperature Rar	nge	-55 to +150	°C
T _L	Maximum lead temperature for soldering 1/8" from case for 5 seconds	j purposes,	300	°C

Thermal Characteristics

Symbol	Parameter	FQP2N40_F080	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	3.13	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQP2N40-F080	FQP2N40	TO-220	Tube	N/A	N/A	50 units

Electrical Characteristics T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	400			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.4		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 400 V, V _{GS} = 0 V			1	μΑ
	zero Gate voltage Drain Current	V _{DS} = 320 V, T _C = 125°C			10	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 0.9 A		4.5	5.8	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 50 \text{ V}, I_{D} = 0.9 \text{ A}$		1.1		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,	 115	150	pF
Coss	Output Capacitance	f = 1.0 MHz	 20	30	pF
C _{rss}	Reverse Transfer Capacitance		 3	4	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DD} = 200 V, I _D = 1.8 A,	 7	25	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$	 30	70	ns
t _{d(off)}	Turn-Off Delay Time	3	 7	25	ns
t _f	Turn-Off Fall Time	(Note 4)	 25	60	ns
Q_g	Total Gate Charge	V _{DS} = 320 V, I _D = 1.8 A,	 4.0	5.5	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 10 V	 1.1		nC
Q_{gd}	Gate-Drain Charge	(Note 4)	 2.1		nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current		 	1.8	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		 	7.2	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 1.8 A	 	1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 1.8 \text{ A},$	 160		ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs	 0.4		μC

- Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 45 mH, I_{AS} = 1.8 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25°C. 3. $I_{SD} \le$ 1.8 A, $di/dt \le$ 200 A/ μ s, $V_{DD} \le$ BV $_{DSS}$, starting T_{J} = 25°C.

- 4. Essentially independent of operating temperature.

Typical Characteristics

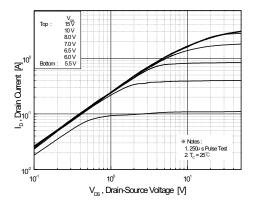


Figure 1. On-Region Characteristics

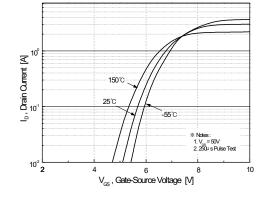


Figure 2. Transfer Characteristics

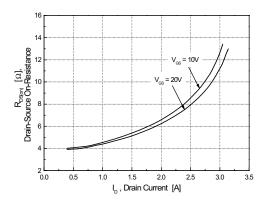


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

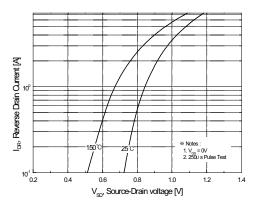


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

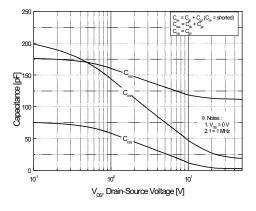


Figure 5. Capacitance Characteristics

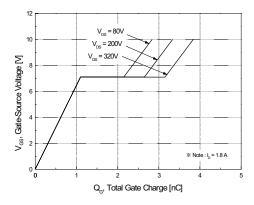


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

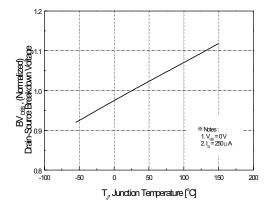


Figure 7. Breakdown Voltage Variation vs. Temperature

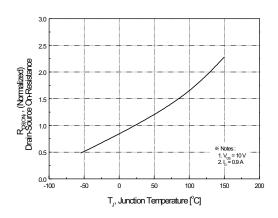


Figure 8. On-Resistance Variation vs. Temperature

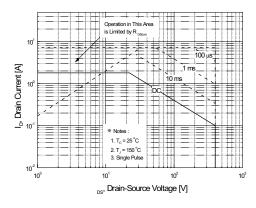


Figure 9. Maximum Safe Operating Area

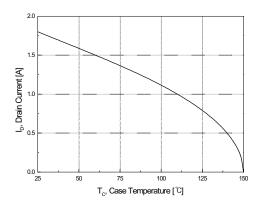


Figure 10. Maximum Drain Current vs. Case Temperature

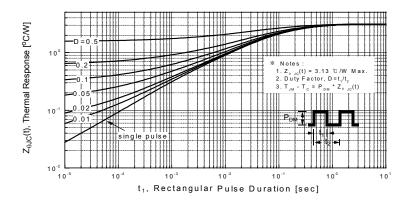


Figure 11. Transient Thermal Response Curve

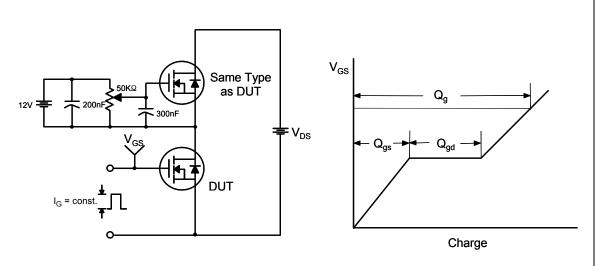


Figure 12. Gate Charge Test Circuit & Waveform

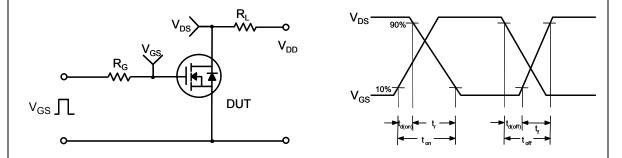


Figure 13. Resistive Switching Test Circuit & Waveforms

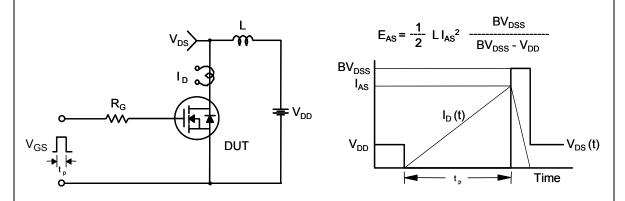


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

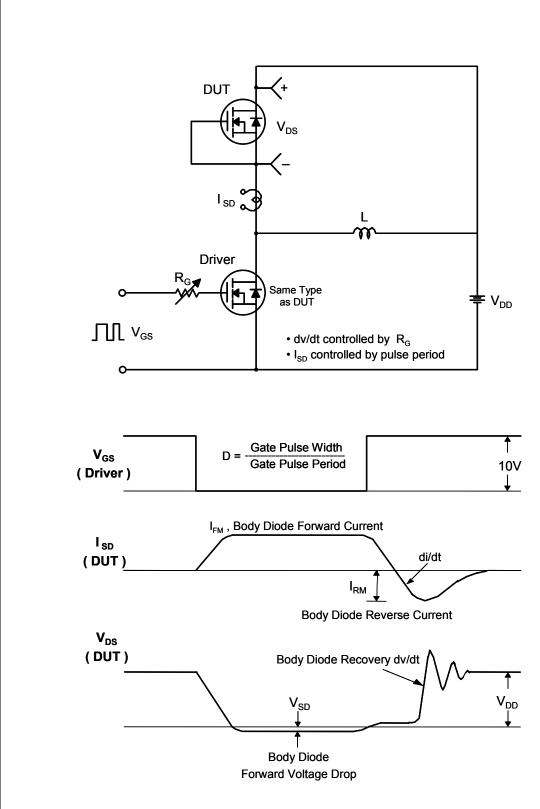
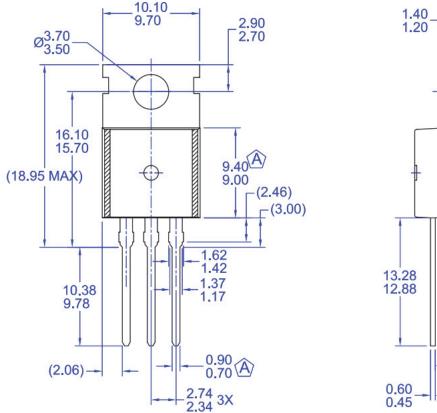
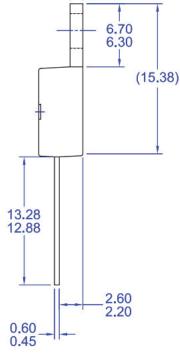
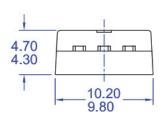


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions







NOTES:

- (A) CONFORMS TO JEDEC TO-220 VARIATION AB EXCEPT WHERE NOTED
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DRAWING FILE/REVISION: MKT-TO220Y03REV1

Figure 16. TO220, Molded, 3-Lead, Jedec Variation AB

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